

**IN THE CLAIMS:**

**PI as cancel claims 1-20..**

**Kindly add the following new claims 21-43:**

21. A module comprising:

a substrate having a lateral side<sup>62</sup>, an upper side and a lower side;  
a recess in said lateral side; and  
an electrode in said recess and spaced from said lateral side.

22. The module according to claim 21, further comprising:

an electronic component mounted on said substrate.

23. The module according to claim 22, further comprising:

a land, on said upper side, adjacent said recess and connected to said electrode;

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and

a land, on said lower side, adjacent said recess and connected to said electrode.

24. The module according to claim 22, wherein

said substrate comprises a multi-layer substrate that includes an internal layer having thereon an internal pattern and a land adjacent said electrode, with said land being connected to said internal pattern and said electrode.

25. The module according to claim 22, further comprising:

another electrode at said lateral side.

26. The module according to claim 22, wherein said substrate has a corner, and further comprising:

another electrode at said corner.

27. The module according to claim 22, wherein  
said recess is formed from plural recesses that extend from said upper side to said lower side.

28. The module according to claim 27, further comprising:  
a metal shield case covering said electronic component, said metal shield case having a leg joined to said electrode.

29. The module according to claim 28, wherein  
said lateral side is positioned outwardly beyond said metal shield case.

30. The module according to claim 28, wherein  
said metal shield case has a lateral side, with said lateral side of said substrate being substantially flush and parallel with said lateral side of said metal shield case.

31. The module according to claim 28, wherein  
said metal shield case has a lateral side and an upper side, with said lateral side of said metal shield case being more textured than said upper side of said metal shield case.

32. The module according to claim 28, wherein  
said leg is soldered to said electrode.

33. The modul according to claim 21, wherein  
said lateral side defines a surface, and said electrode is spaced from said lateral  
side such that said ~~no~~ portion of said electrode is co-planar with said surface.

34. A method comprising:

forming a hole in a mother board from which substrates are to be provided by  
cutting said mother board;

forming a metal plated portion on said mother board around said hole and on an  
interior surface of said hole;

covering said metal plated portion with a resist;

curing said resist;

placing a mask over said resist so as to expose regions of said resist, which regions  
include portions of said resist that are positioned over part of said metal plated portion on  
said interior surface of said hole;

subjecting the exposed regions of said resist to light so as to decompose said  
exposed regions of said resist;

removing the decomposed exposed regions of said resist so as to expose the part  
of said metal plated portion on said interior surface of said hole over which the exposed  
portions of said resist were positioned; and

removing the exposed part of said metal plated portion from said interior surface of  
said hole.

35. The method according to claim 34, further comprising:

cutting said mother board through portions of said interior surface of said hole from  
which said exposed part of said metal plated portion was removed.

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cont

36. The method according to claim 34, wherein forming a hole in a mother board comprises forming a hole at a location that is to correspond to a corner of a substrate to be provided by cutting said mother board.

37. The method according to claim 34, wherein forming a hole in a mother board comprises forming a slot in said mother board by consecutively drilling round holes.

38. The method according to claim 37, wherein consecutively drilling round holes comprises first drilling a first hole, then drilling a second hole, and then drilling a third hole, with said third hole being positioned between said first and second holes.

39. A method comprising:  
forming a hole in a mother board from which substrates are to be provided by cutting said mother board;  
forming a metal plated portion on said mother board around said hole and on an interior surface of said hole;  
covering said metal plated portion with a resist;  
placing a mask over said resist so as to expose regions of said resist while covering other regions of said resist, which other regions include portions of said resist that are positioned over part of said metal plated portion on said interior surface of said hole;  
subjecting the exposed regions of said resist to light so as to cure said exposed regions of said resist while leaving the covered regions of said resist uncured;  
removing the uncured regions of said resist so as to expose the part of said metal plated portion on said interior surface of said hole over which the covered portions of said resist were positioned; and

removing the exposed part of said metal plated portion from said interior surface of said hole.

40. The method according to claim 39, further comprising:  
cutting said mother board through portions of said interior surface of said hole from which said exposed part of said metal plated portion was removed.

41. The method according to claim 39, wherein  
forming a hole in a mother board comprises forming a hole at a location that is to correspond to a location where four adjacent substrates are to meet upon cutting said mother board.

42. The method according to claim 39, wherein  
forming a hole in a mother board comprises forming a slot in said mother board by consecutively drilling round holes.

43. The method according to claim 42, wherein  
consecutively drilling round holes comprises first drilling a first hole, then drilling a second hole, and then drilling a third hole, with said third hole being positioned between said first and second holes.

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